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## **Corporate Application**

sponsor's name, can be attached.

(2/12)

American Society for Composites, c/o Prof. Tom Whitney, Treasurer Civil Engineering Dept., 422 Kettering Lab, Univ. of Dayton, 300 College Park Dayton, OH 45469-0243 email: <a href="mailto:twhitney1@udayton.edu">twhitney1@udayton.edu</a> phone 937-229-2980, fax 937-229-3491, <a href="mailto:www.asc-composites.org">www.asc-composites.org</a>

Application for:			
	) Corporation interested in the Shall provide a single point o	development and application of composites. f contact.	
Contact Information			
Last Name	First Name	Middle Name	
Job Title	Divisi	on or Department	
Phone Number	Fax Number	E-mail	
Organization Informatio	n		
Company, Organization, or Agency		Division or Department	
Work Address			
City	State Zi	) URL	
General Phone Number	General Fax Number	General E-mail	
Corporate Interests			
Authorized Signature		<ul><li>Instructions:</li><li>Send this form and accompanying payment to</li></ul>	
		Prof. Tom Whitney at the address above. Form can be transmitted via email, fax, or mail. Payment can be made online via <i>PayPal</i> , or by check/money-	
Signature (electronic OK)	Date	order payable to <b>ASC</b> and mailed together with this	
Additional payment information (if s	ent separately):	form. If paid online, send copy (or PDF "print") of	